

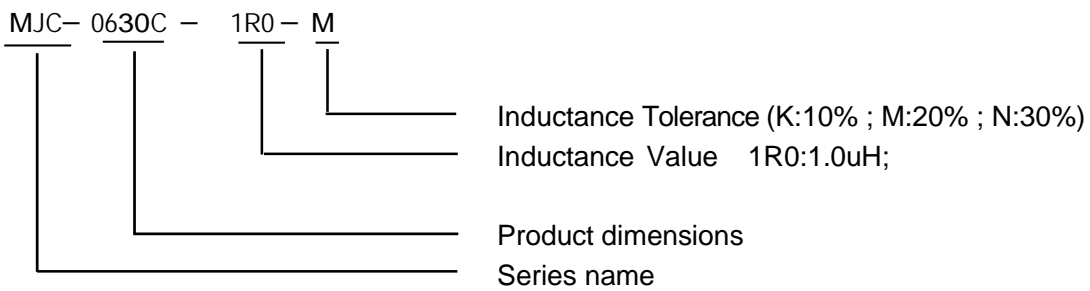
1. Features

- Low profile and low DCR.
- Shielded construction.
- handles high transient current spikes without saturation
- frequency up to 3MHz
- Ultra Low buzz noise, due to composite construction
- 100% lead (Pb) free meet RoHS standard

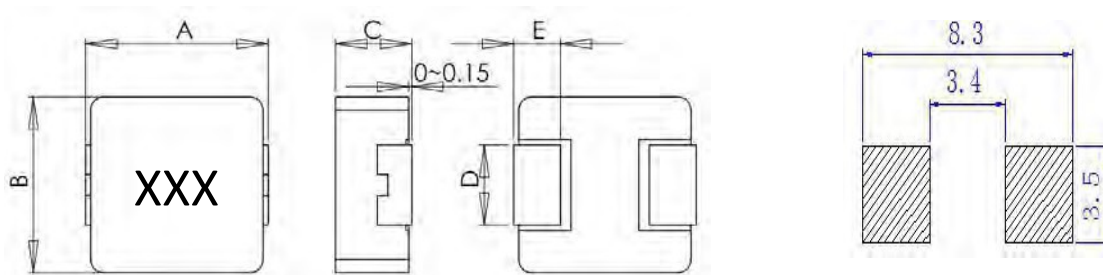
2. Applications

- PDA/Notebook/Desktop, and server applications.
- Low profile,high current power supplies.
- Battery powered devices.
- DC/DC converters.

3. Product Identification



4. Shapes And Dimensions



ITEM	A	B	C	D	E
SPEC	7.0±0.5	6.6±0.2	3.0 MAX	3.0±0.3	1.6±0.3

5. Electrical Characteristics

Part number	Inductance (uH)	Rdc (mΩ)		Heat Rating Current DC Amps. Idc (A)	Saturation Current DC Amps. Isat (A)
	100KHz/0.25V	Typical	Max	Max	Max
MJC-0630C-R10-M	0.10±20%	1.50	1.70	32.50	60.00
MJC-0630C-R15-M	0.15±20%	1.90	2.50	30.00	40.00
MJC-0630C-R22-M	0.22±20%	2.50	3.00	21.00	34.00
MJC-0630C-R33-M	0.33±20%	3.00	3.50	21.00	25.00
MJC-0630C-R47-M	0.47±20%	3.50	4.10	18.00	20.00
MJC-0630C-R56-M	0.56±20%	4.25	4.90	15.00	18.00
MJC-0630C-R68-M	0.68±20%	5.00	5.70	14.00	17.00
MJC-0630C-R82-M	0.82±20%	6.00	6.90	12.00	16.00
MJC-0630C-1R0-M	1.00±20%	7.00	7.50	11.00	15.00
MJC-0630C-1R2-M	1.20±20%	8.00	10.50	10.00	14.00
MJC-0630C-1R5-M	1.50±20%	10.60	12.10	9.00	14.00
MJC-0630C-2R2-M	2.20±20%	15.50	17.50	7.00	10.00
MJC-0630C-3R3-M	3.30±20%	23.00	26.00	6.00	9.50
MJC-0630C-4R7-M	4.70±20%	34.50	38.00	5.50	6.50
MJC-0630C-5R6-M	5.60±20%	36.00	42.00	5.00	6.25
MJC-0630C-6R8-M	6.80±20%	43.00	50.00	5.00	6.00
MJC-0630C-8R2-M	8.20±20%	58.50	65.00	4.50	6.00
MJC-0630C-100-M	10.00±20%	64.00	68.00	4.50	5.50
MJC-0630C-120-M	12.00±20%	85.00	98.00	3.50	5.00
MJC-0630C-150-M	15.00±20%	98.00	115.0	3.00	4.50
MJC-0630C-220-M	22.00±20%	135.0	165.0	2.30	3.10
MJC-0630C-330-M	33.00±20%	225.0	257.0	2.00	2.50
MJC-0630C-390-M	39.0±20%	270.0	310.0	1.80	2.20
MJC-0630C-470-M	47.0±20%	328.0	350.0	1.50	2.00

(1) All test data is referenced to 25°C ambient .

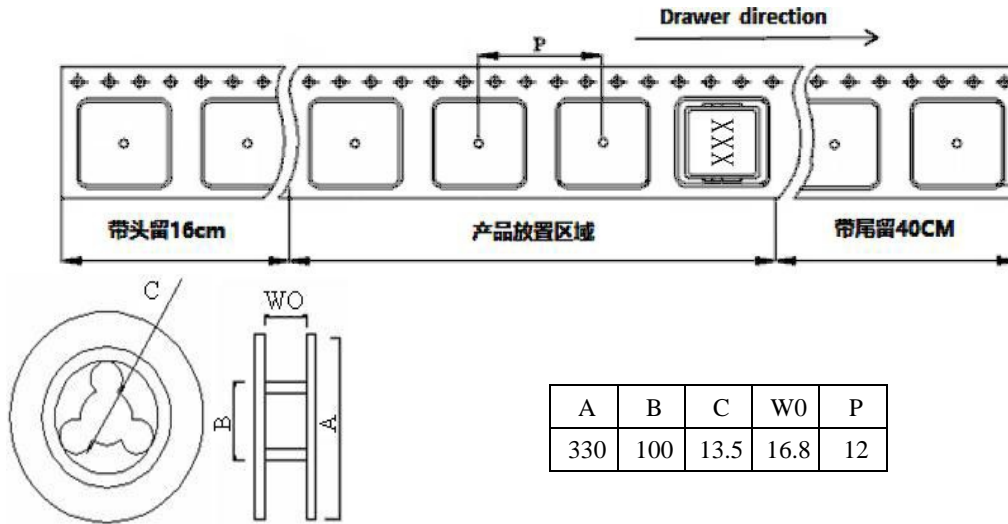
(2) When applying the heat rating current DC (Idc) to coil, it will cause an approximate ΔT of 40°C.

(3) When applying the saturation current DC(Isat) to coil, it will cause the initial inductance value to drop 30% Typical.

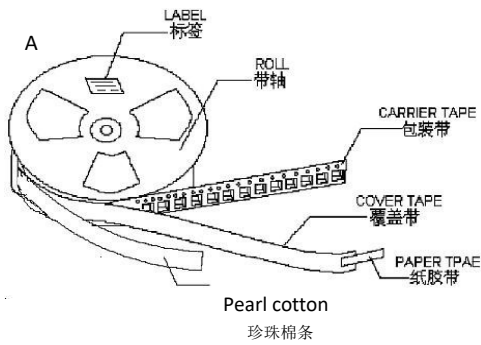
(4) Operating Temperature Range -40°C to +125°C

6. Packaging Information

(1) Tape & Reel Dimension



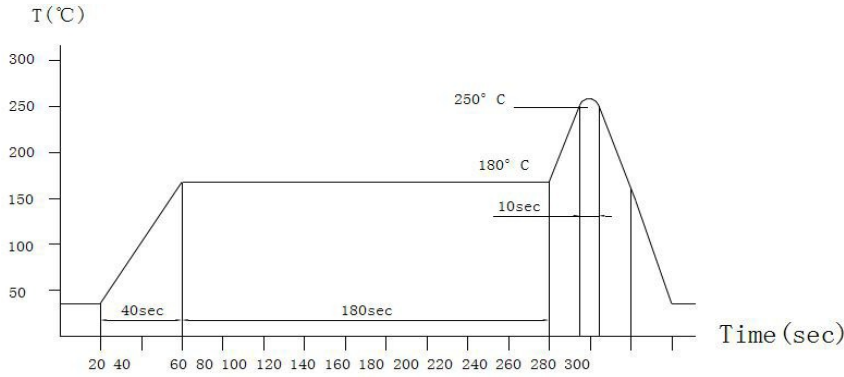
(2) The packing way and quantity



1500 pcs/Reel

7. Soldering and Mounting

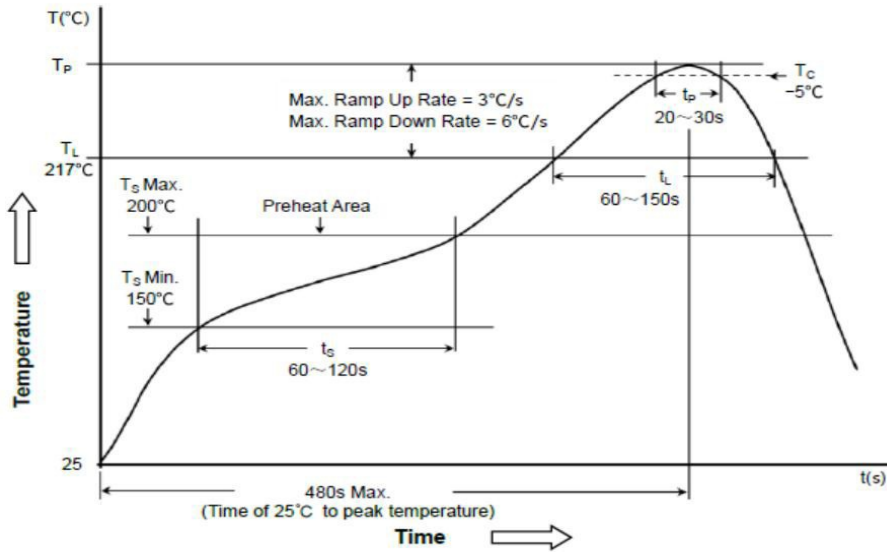
(1). Recommended Reflow Conditions (Lead-free)



The above recommended reflow test conditions are based on the company's reflow welding equipment

(2). Reflow Soldering Heat Endurance

Reflow profile for SMT components
SMT 回流焊温度曲线



Classification of peak package body temperature (T_p)
封装体峰值温度(T_p)分类

	Package Thickness 封装厚度	Package Volume 封装体积		
		<350 mm ³	350~2000 mm ³	>2000 mm ³
PB-Free Assembly 无铅装配	<1.6mm	260°C	260°C	260°C
	1.6~2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

- Reflow soldering is carried out under this condition and placed under normal temperature and humidity conditions
- Twice reflow test is acceptable with the test interval remaining 1 hour under the normal conditions.
- The reflow test profile may vary with the testing instruments.

8. Reliability Test

Item	Performance	Test Condition
Solder Ability Test	More than 90% of terminal electrode should be covered with solder.	Terminal in flux and then into 245 + 5 °C tin furnace 5 seconds
Terminal Strength	the terminal should not peel off	After soldering between copper plate and electrode. sample is pushed in three directions of X,Y and Z with force of 5N(0.5kgf) for 10±5 seconds
Vibration	1.No separation or indication of electrode. 2.No case deformation or change in appearance.	Inductance deviation within +10% after vibration for 1 hour. In each of three orientations at Sweep vibration (10~55~10HZ) with 1.5mmP-P amplitudes.
Drop Test	1.The inductance deviation is within +10%. 2.No case deformation or change in appearance.	981m/s ² (100G) is used to automatically drop the product at a height of 1 meter after packaging. and there are three different directions
High Temperature Storage Test	1.No case deformation or change in appearance 2.ΔL/L ≤ 10% 3.ΔDCR/DCR ≤ 10%	Temperature:125°C±3°C Time:500±2 hours. Tested not less than 1 hour, nor more than 2 hours at room
Low Temperature Storage Test	1.No case deformation or change in appearance 2.ΔL/L ≤ 10% 3.ΔDCR/DCR ≤ 10%	Temperature:-40°C±3°C Time:500±2 hours. Tested not less than 1 hour, nor more than 2 hours at room.
High Temperature Humidity Test	1.No case deformation or change in appearance 2.ΔL/L ≤ 10% 3.ΔQ/Q ≤ 30% 4.ΔDCR/DCR ≤ 10%	Temperature:85°C±3°C. Humidity:85±5%RH Test Time:500±2 hours Tested not less than 1 hour. Nor more than 2 hours at room temperature
Thermal Shock Test Storage Test	1.No case deformation or change in appearance 2.ΔL/L ≤ 10% 3.ΔDCR/DCR ≤ 10%	First-40°C for 30 Minutes, last 125°C for 30 Minutes as 1 cycle. Go through 20 cycles.